

AMENDMENT TO THE CLAIMS:

The following claim set replaces all prior versions, and listings, of claims in the application:

1. (Currently Amended) Process for producing a molded structure of a polyamide layer and a polyolefin layer, comprising blow-moulding a multilayer film containing at least a branched polyamide layer and a polyolefin layer directly connected to the polyamide layer or connected to the polyamide layer by an adhesive layer, wherein said branched polyamide layer ~~consisting essentially~~ consists of a branched polyamide, and said polyolefin layer ~~consisting~~ consists essentially of polypropylene or LLDPE containing at most 5% of another polyethylene, ~~characterized in that a branched polyamide is used as polyamide.~~
- 2-4. (Cancelled)
5. (Currently Amended) Multilayer blow-moulded film comprising at least a polyamide layer and a polyolefin layer directly connected to the polyamide layer or connected to the polyamide layer by an adhesive layer, wherein the polyamide layer consists ~~essentially~~ of a branched polyamide, and wherein the polyolefin layer consists essentially of polypropylene or of polyethylene, which polyethylene layer, other than the adhesive layer, if present, contain only polyethylene which is at least 95% linear low-density polyethylene.
- 6 - 7. (Cancelled)
8. (Previously Presented) Multilayer film according to claim 5, wherein the polyolefin layer consists essentially of linear polypropylene.

9. (Previously Presented) Multilayer film according to claim 5, wherein the polyolefin layer consists essentially of linear low density polyethylene.
10. (Previously Presented) Multilayer film according to claim 9, wherein the polyolefin layer includes essentially 0% of another polyethylene characterized by good bubble stability in a blow molding process.
11. (Previously Presented) Multilayer film according to claim 5, wherein the polyolefin layer consists of linear low density polyethylene alone or in mixture with up to 50% of modified linear low density polyethylene adhesion modifier, as the only polyolefin material(s).
12. (Previously Presented) Multilayer film according to claim 5, having a total thickness in the range of from 20 to 300 μm .
13. (Previously Presented) Multilayer film according to claim 5, wherein the polyolefin layer has a thickness of from 10 μm to about 100 μm .
14. (Previously Presented) Multilayer film according to claim 13, wherein the polyamide layer has a thickness of from 2 to 150 μm .
15. (Previously Presented) Multilayer film according to claim 13, wherein the polyamide film has a thickness of at least 20% of the thickness of the polyolefin layer up to 100 μm .
16. (Previously Presented) A blown film comprising the multilayer film according to claim 5.
17. (Previously Presented) Blown film according to claim 16, wherein the blown film has a blow-up ratio of from 20 to 40%.
18. (Previously Presented) Process according to claim 1, wherein the polyolefin layer consists essentially of linear polypropylene.

19. (Previously Presented) Process according to claim 1, wherein the polyolefin layer consists essentially of linear low density polyethylene.
20. (Previously Presented) Process according to claim 19, wherein the polyolefin layer includes essentially 0% of another polyethylene characterized by good bubble stability in a blow molding process.
21. (Previously Presented) Process according to claim 1, wherein the polyolefin layer consists of linear low density polyethylene alone or in mixture with up to 50% of modified linear low density polyethylene adhesion modifier, as the only polyolefin material(s)
22. (Previously Presented) Process according to claim 1, wherein the blow-molded multilayer film has a total thickness in the range of from 20 to 300 μm .
23. (Previously Presented) Process according to claim 1, wherein the polyolefin layer of the blow-molded multilayer film has a thickness of from 10 μm to about 100 μm .
24. (Previously Presented) Process according to claim 23, wherein the polyamide layer has a thickness of from 2 to 150 μm .
25. (Previously Presented) Process according to claim 23, wherein the polyamide film has a thickness of at least 20% of the thickness of the polyolefin layer up to 100 μm .